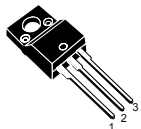
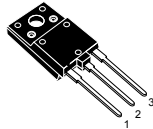




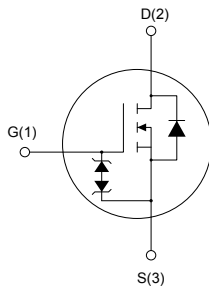
N-channel 600 V, 78 mΩ typ., 34 A MDmesh M2 Power MOSFET in a TO-220FP and TO-3PF packages



TO-220FP



TO-3PF



AM01476v1



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STF40N60M2	600 V	88 mΩ	34 A
STFW40N60M2			

- Extremely low gate charge
- Excellent output capacitance (C_{oss}) profile
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

These devices are N-channel Power MOSFETs developed using the MDmesh M2 technology. Thanks to their strip layout and improved vertical structure, these devices exhibit low on-resistance and optimized switching characteristics, rendering them suitable for the most demanding high-efficiency converters.

Product status links

[STF40N60M2](#)

[STFW40N60M2](#)

Product summary

Order code	STF40N60M2
Marking	40N60M2
Package	TO-220FP
Packing	Tube
Order code	STFW40N60M2
Marking	40N60M2
Package	TO-3PF
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-220FP	TO-3PF	
V_{DS}	Drain-source voltage	600		V
V_{GS}	Gate-source voltage	± 25		V
I_D	Drain current (continuous) at $T_C = 25\text{ }^{\circ}\text{C}$	34		A
I_D	Drain current (continuous) at $T_C = 100\text{ }^{\circ}\text{C}$	22		A
$I_{DM}^{(1)}$	Drain current (pulsed)	136		A
P_{TOT}	Total power dissipation at $T_C = 25\text{ }^{\circ}\text{C}$	40	63	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15		V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50		V/ns
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink ($t = 1\text{ s}$; $T_C = 25\text{ }^{\circ}\text{C}$)	2.5	3.5	kV
T_{stg}	Storage temperature range	-55 to 150		$^{\circ}\text{C}$
T_J	Operating junction temperature range			

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 34\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$, $V_{DS}(\text{peak}) < V_{(BR)DSS}$, $V_{DD} = 400\text{ V}$.
3. $V_{DD} = 480\text{ V}$.

Table 2. Thermal data

Symbol	Parameter	Value		Unit
		TO-220FP	TO-3PF	
R_{thJC}	Thermal resistance, junction-to-case	3.13	2	$^{\circ}\text{C}/\text{W}$
R_{thJA}	Thermal resistance, junction-to-ambient	62.5	50	$^{\circ}\text{C}/\text{W}$

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_J max.)	6	A
E_{AS}	Single pulse avalanche energy (starting $T_J = 25\text{ }^{\circ}\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	500	mJ

2 Electrical characteristics

($T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	600	-	-	V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 600\text{ V}$	-	-	1	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 600\text{ V}$, $T_C = 125\text{ }^{\circ}\text{C}^{(1)}$	-	-	100	μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 25\text{ V}$	-	-	± 10	μA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 17\text{ A}$	-	78	88	Ω

1. Specified by design, not tested in production.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	2500	-	pF
C_{oss}	Output capacitance		-	117	-	pF
C_{rss}	Reverse transfer capacitance		-	2.4	-	pF
$C_{oss\text{ eq.}}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0\text{ to }480\text{ V}$, $V_{GS} = 0\text{ V}$	-	342	-	pF
Q_g	Total gate charge	$V_{DD} = 480\text{ V}$, $I_D = 4.5\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$ (see the Figure 16. Test circuit for gate charge behavior)	-	57	-	nC
Q_{gs}	Gate-source charge		-	10	-	nC
Q_{gd}	Gate-drain charge		-	25.5	-	nC
R_g	Intrinsic gate resistance	$f = 1\text{ MHz}$, $I_D = 0\text{ A}$	-	4.4	-	Ω

1. $C_{oss\text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}$, $I_D = 34\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$ (see the Figure 15. Test circuit for resistive load switching times and Figure 20. Switching time waveform)	-	20.5	-	ns
t_r	Rise time		-	13.5	-	ns
$t_{d(off)}$	Turn-off delay time		-	96	-	ns
t_f	Fall time		-	11	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-	34	-	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-	136	-	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 34\text{ A}$, $V_{GS} = 0\text{ V}$	-	-	1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 34\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$ (see the Figure 17. Test circuit for inductive load switching and diode recovery times)	-	440	-	ns
Q_{rr}	Reverse recovery charge		-	8.2	-	μC
I_{RRM}	Reverse recovery current		-	37	-	A
t_{rr}	Reverse recovery time	$I_{SD} = 34\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, $T_J = 150\text{ }^\circ\text{C}$ (see the Figure 17. Test circuit for inductive load switching and diode recovery times)	-	568	-	ns
Q_{rr}	Reverse recovery charge		-	11.5	-	μC
I_{RRM}	Reverse recovery current		-	40.5	-	A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area for TO-220FP

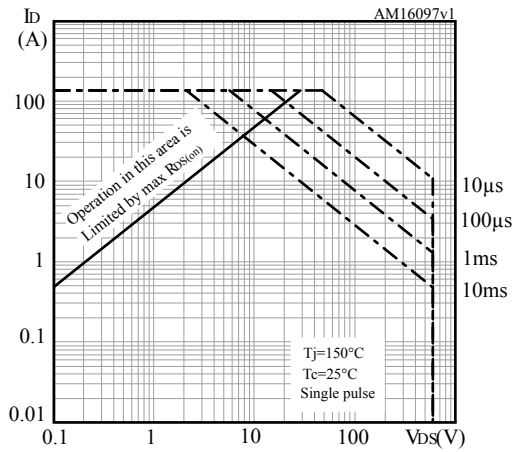


Figure 2. Normalized transient thermal impedance for TO-220FP

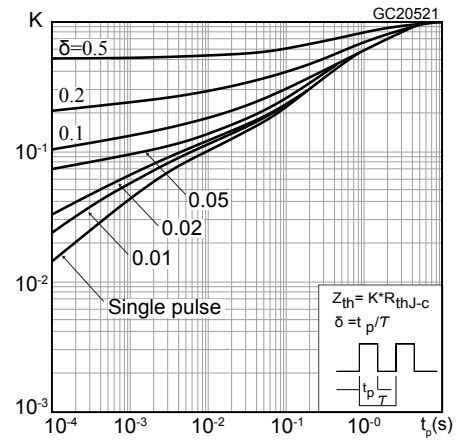


Figure 3. Safe operating area for TO-3PF

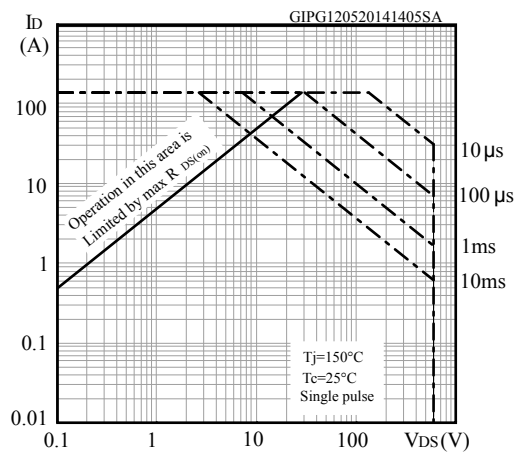


Figure 4. Normalized transient thermal impedance for TO-3PF

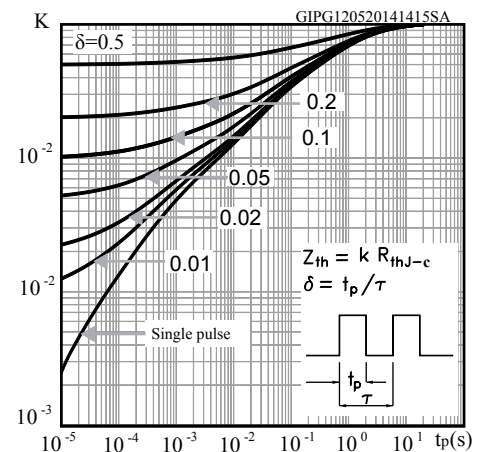


Figure 5. Typical output characteristics

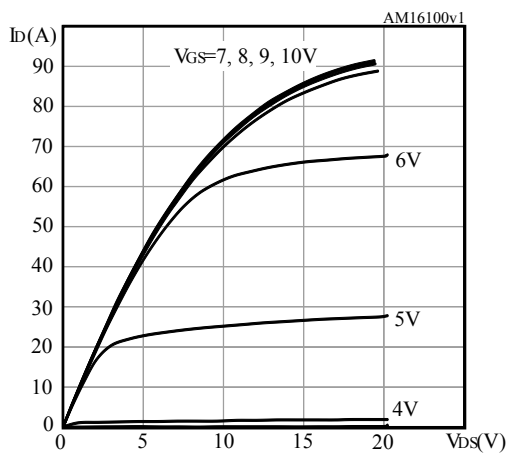


Figure 6. Typical transfer characteristics

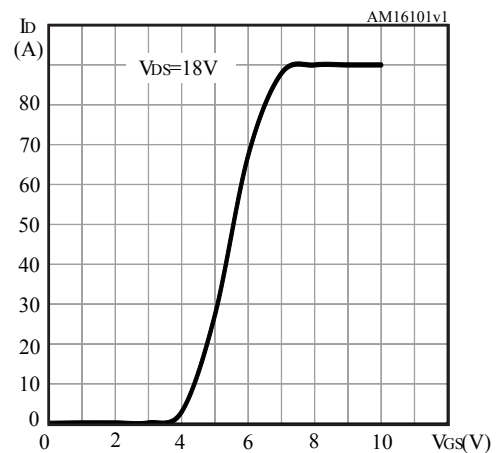


Figure 7. Typical gate charge characteristics

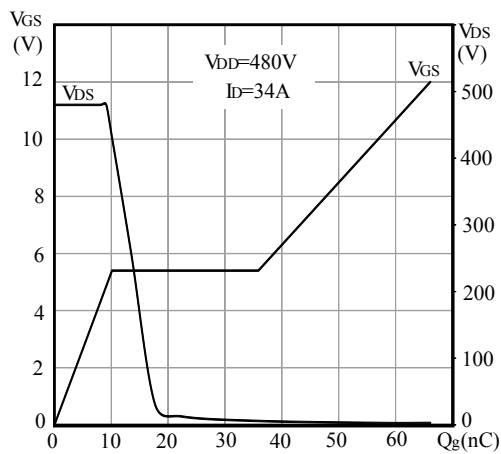


Figure 8. Typical drain-source on-resistance

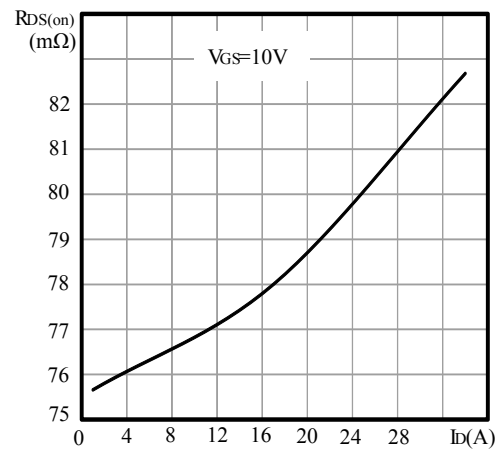


Figure 9. Typical capacitance characteristics

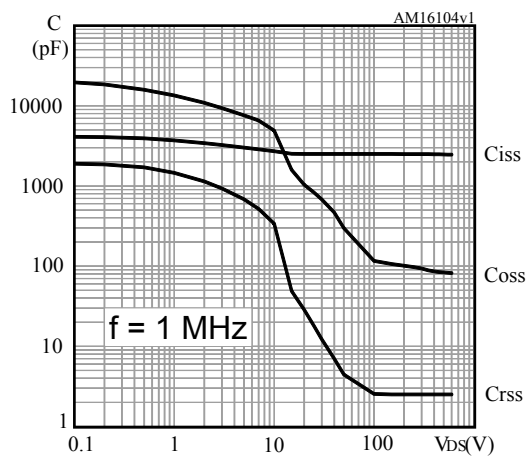


Figure 10. Typical output capacitance stored energy

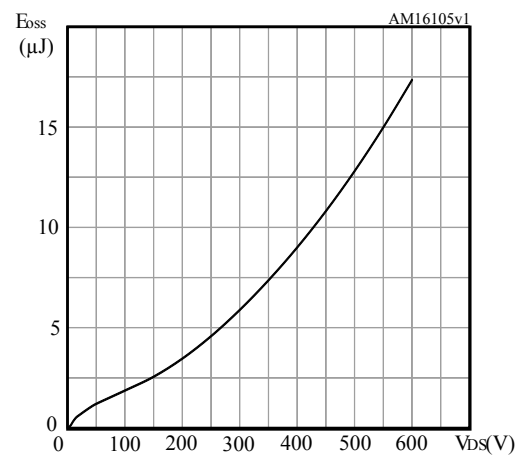


Figure 11. Normalized gate threshold vs temperature

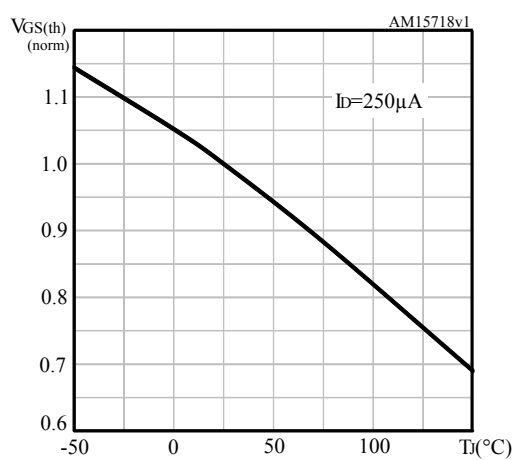


Figure 12. Normalized on-resistance vs temperature

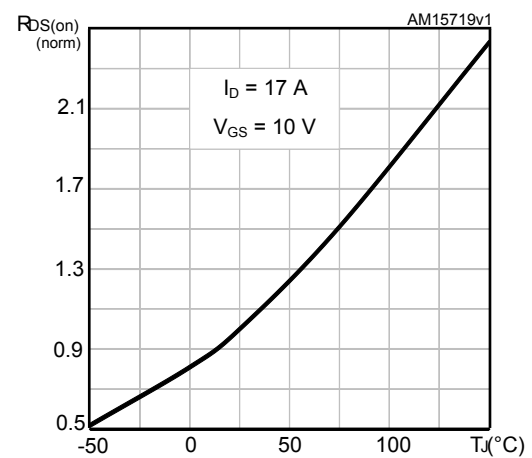


Figure 13. Normalized breakdown voltage vs temperature

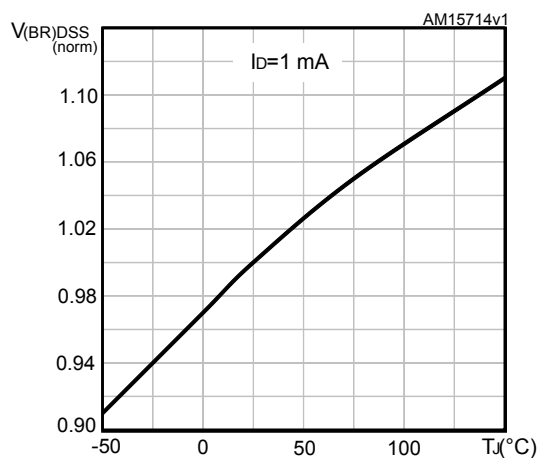
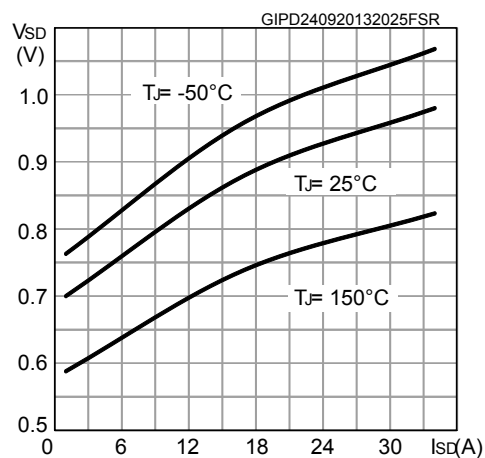
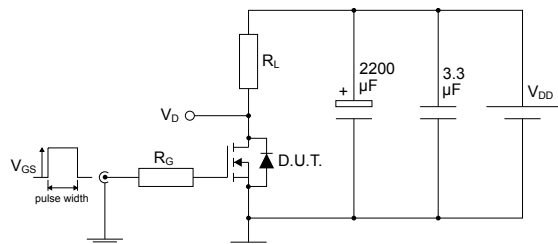


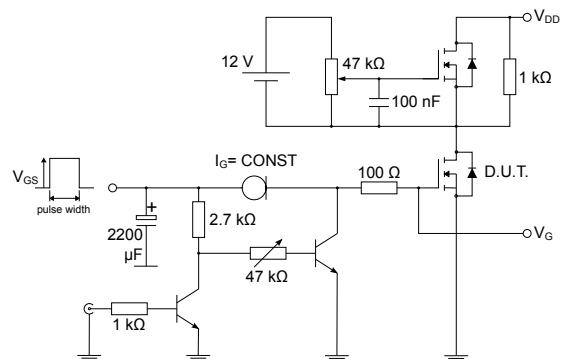
Figure 14. Typical reverse diode forward characteristics



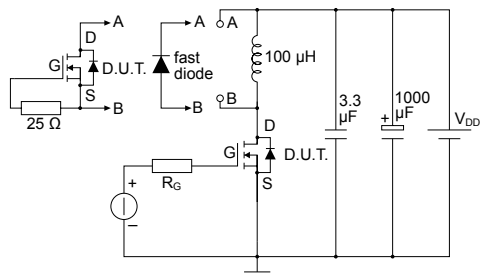
3 Test circuits

Figure 15. Test circuit for resistive load switching times


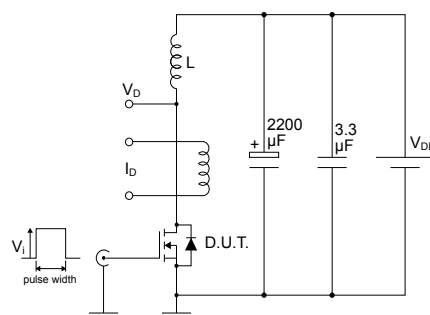
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Figure 16. Test circuit for gate charge behavior


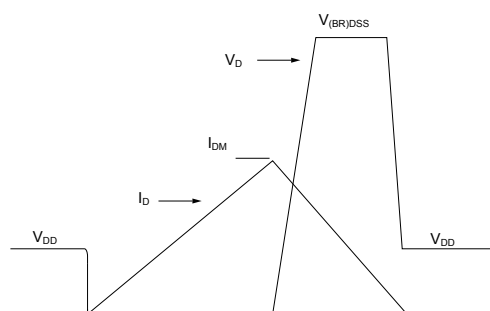
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Figure 17. Test circuit for inductive load switching and diode recovery times


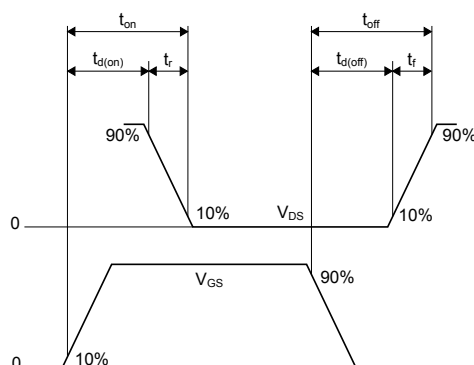
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Figure 18. Unclamped inductive load test circuit


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Figure 19. Unclamped inductive waveform


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Figure 20. Switching time waveform


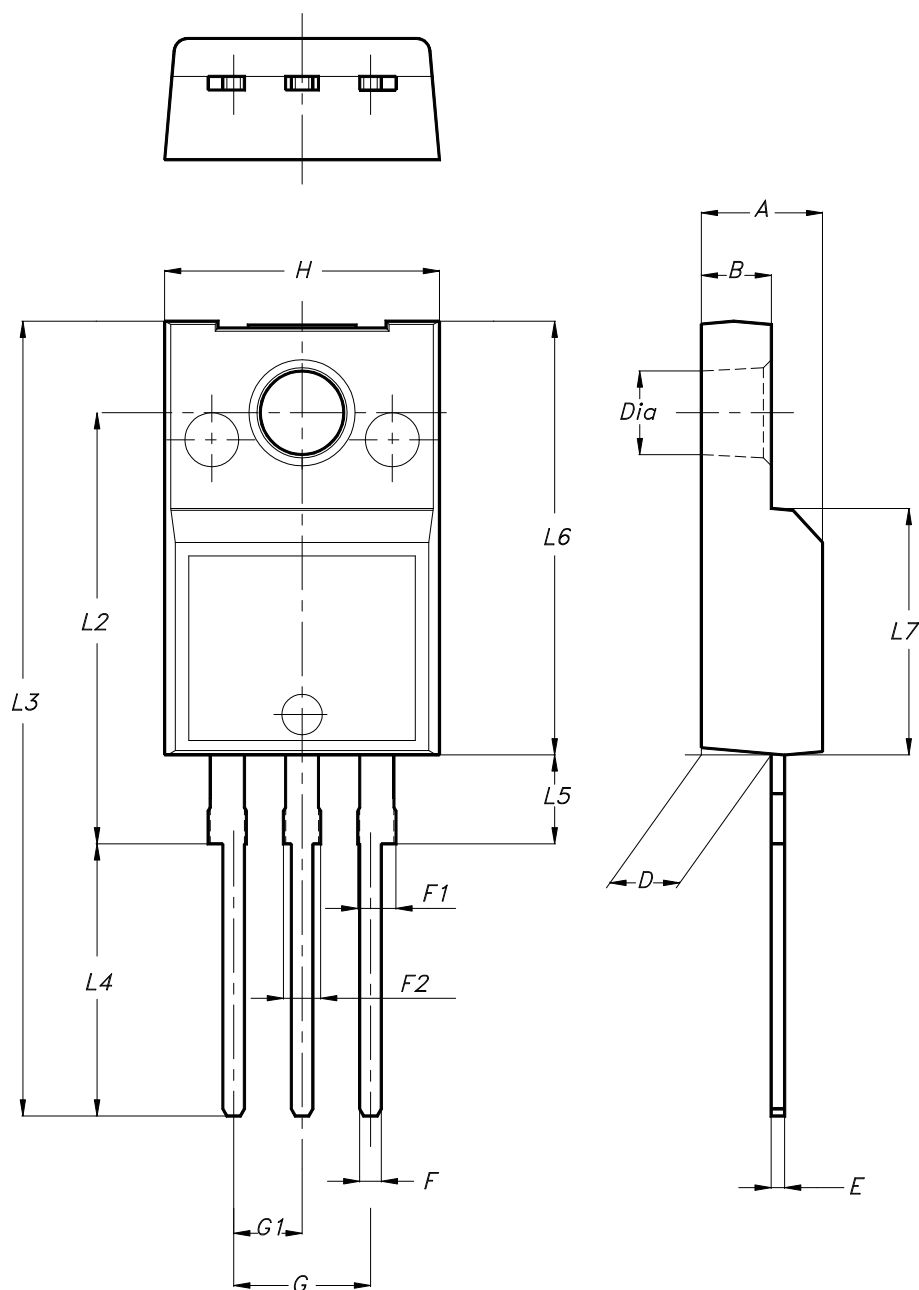
AM01473v1

4 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-220FP type B package information

Figure 21. TO-220FP type B package outline



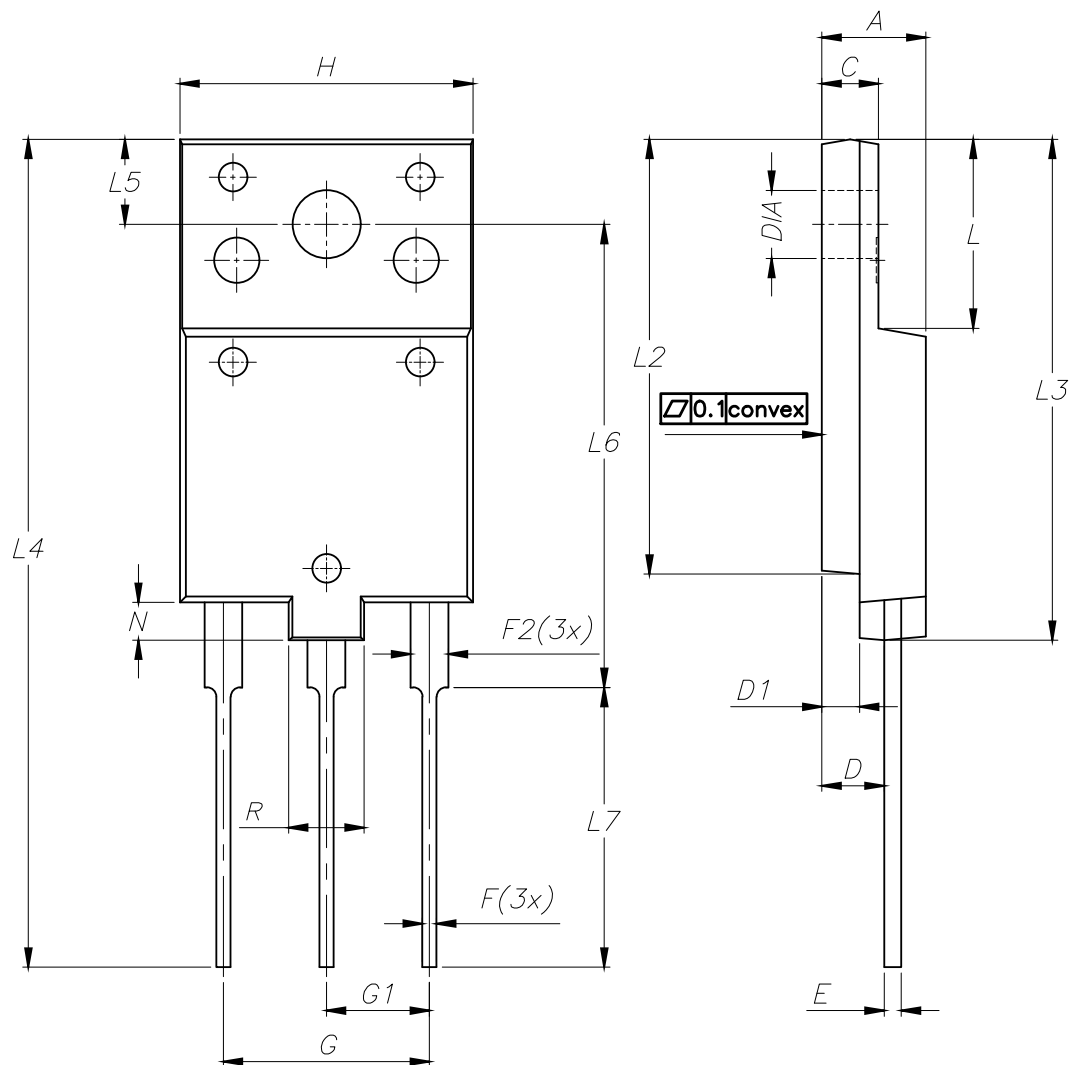
7012510_B_rev.14

Table 8. TO-220FP type B package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

4.2 TO-3PF type A package information

Figure 22. TO-3PF type A package outline



7627132_type_A_9

Table 9. TO-3PF type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.00
F	0.65		0.85
F2	1.80		2.20
G	10.80		11.00
G1	5.35	5.45	5.55
H	15.30		15.70
L	9.80	10.00	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.60		44.00
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15.00
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80

Revision history

Table 10. Document revision history

Date	Revision	Changes
15-May-2014	1	First release. Part numbers STF40N60M2 and STFI40N60M2 previously included in datasheet DocID024932.
28-Sep-2016	2	Updated title in cover page. Updated <i>Table 2: Absolute maximum ratings</i> , <i>Table 5: On /off states</i> , <i>Table 6: Dynamic</i> and <i>Table 8: Source drain diode</i> . Minor text changes.
03-Dec-2025	3	Removed order code STFI40N60M2. Updated Section 4: Package information . Minor text changes.

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